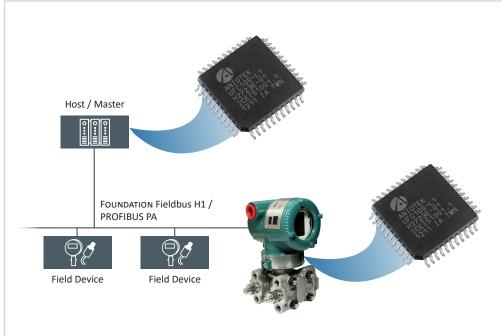


## **UFC100-L1**

# Fieldbus ASIC for Field Devices and Hosts Supporting Foundation™ Fieldbus H1 and PROFIBUS PA

- Implementation of time-critical parts of Foundation Fieldbus (FF) H1 and PROFIBUS PA communication in field devices or host systems
- State-of-the-art hardware with functional advantages
- Support of a special Enhanced Mode feature





#### **Advanced Communication Capabilities**

- Addressing time-critical Physical layer and Data Link layer parts of Foundation Fieldbus H1 or PROFIBUS PA implementations in field devices or host systems
- Work with additional hardware and software, including additional processor for protocol stack execution as well as Media Attachment Unit
- Based on state-of-the-art hardware design using CMOS 3.3V technology
- Advantages like improved jitter tolerance, very low power consumption, and larger FIFO memory with fewer processor interrupts
- Fully pin-compatible with the Yamaha YTZ420 ("FIND1+")

#### Committed to Long-Term Availability and Strict Quality Standards

- Softing commitment to long-term availability
- E.g. provision of migration path to current version after dicontinuation of predecessor's package assembly by semiconductor manufacturer
- Manufacturing and sales using state-of-the-art quality management system complying with ISO 9001:2008
- Assurance of strict product quality standards by DNV certificate

#### **Enhanced Mode Providing Optimized Communication Features**

- Additional communication functionality in fieldbus controller
- More CPU power for application software by reduction of CPU load related to pure bus communication of field device
- Improved frame handling and increased utilization of bus communication capacity by analyzing incoming messages and rejecting irrelevant ones already at fieldbus ASIC level



### **UFC100-L1**

Technical Data			
Applications	FOUNDATION Fieldbus H1	FOUNDATION Fieldbus field device FOUNDATION Fieldbus Host interface FOUNDATION Fieldbus HSE Linking Device	
	PROFIBUS PA	PROFIBUS PA field device PROFIBUS PA Master interface	
Physical Properties	Supply Voltage	2.7 V 3.6 V	
	Operating Current Consumption at 3 V	0.35 mA (1 MHz CLKIN Frequency) 0.65 mA (4 MHz CLKIN Frequency) (all inputs connected to CMOS outputs, all outputs driving CMOS inputs)	
	Operation Temperature	-40 °C +85 °C	
Compliance	Physical Layer	IEC 61158-2 Physical Layer Standard at 31.25 Kbit/s	
	Data Link Layer	IEC 61158-4 Data Link Layer Standard	

Scope of Delivery		
Hardware	Tray of 160 units	
Documentation	User's Manual	

Order Numbers				
IFL-KK-020901	UFC100-L1			

Additional Products and Services				
EAA-KS-020200	FBK-2			
UBA-KK-020501	FOUNDATION Fieldbus H1 Host Stack			
FFH1FD	FOUNDATION Fieldbus H1 Field Device Stack			
TSA-KK-023001	Introductory Training "FOUNDATION Fieldbus" This training is not offered as a standard training course, but tailored to individual customer requirements. It is usually held as part of a workshop and in connection with an integration project.			
TRA-PB-TECH	Training "PROFIBUS Technology"			

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